

F

E

D

C

B

A

F

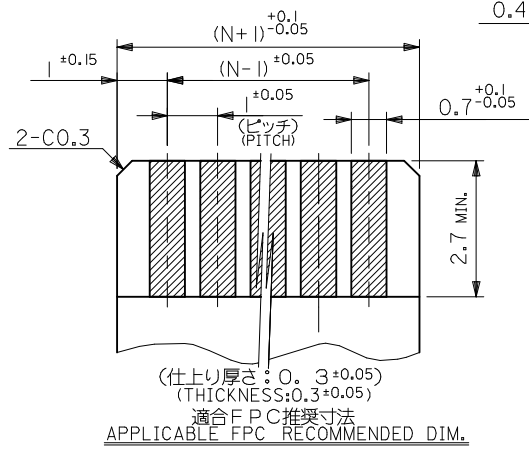
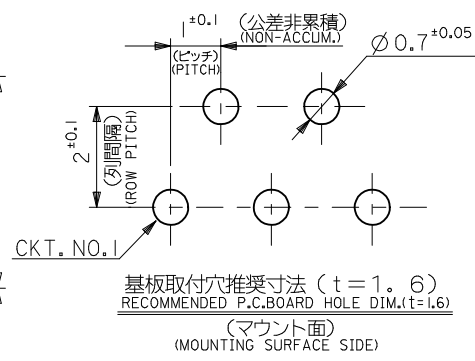
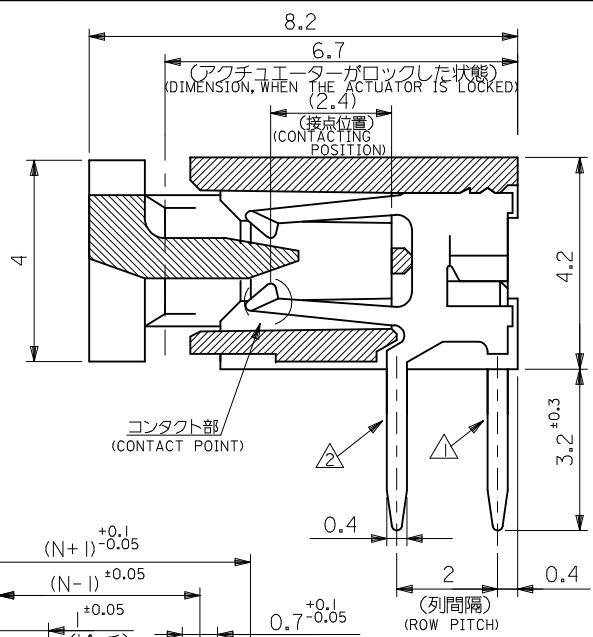
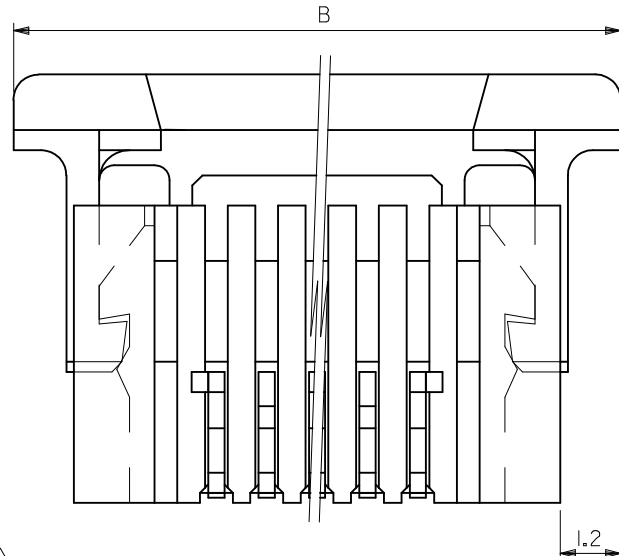
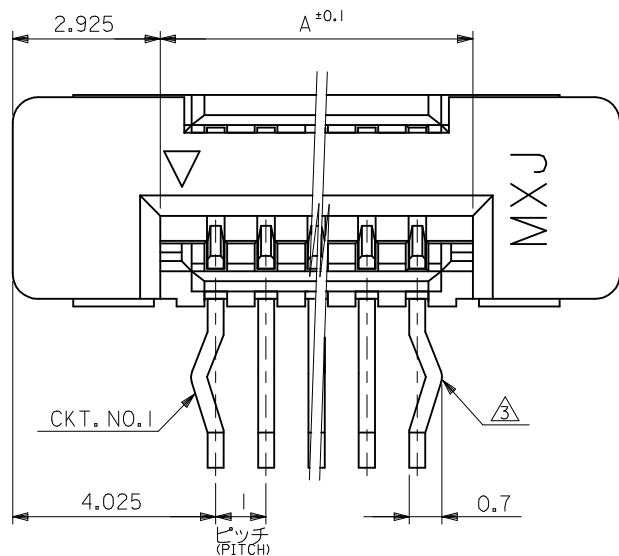
E

D

C

B

A



FPCについて:
 打抜き方向は導体側から補強板を推奨致します。補強フィルム材質はポリアイミドを推奨致します。
 接着剤は熱硬化接着剤を推奨致します。
 ABOUT FPC:
 RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
 RECOMMENDED MATERIAL :
 STIFFENER FILM : POLYIMIDE
 BONDING AGENT :
 THERMOSETTING BONDING AGENT

- 注記:
 NOTES: ① CKT. NO. 1を基準に偶数番目のソルダータール。
 EVEN NUMBER SOLDER TAIL.
 ② CKT. NO. 1を基準に奇数番目のソルダータール。
 ODD NUMBER SOLDER TAIL.
 ③ ソルダータールキックは、△のソルダータールの両端部に設ける。
 KINK TO BE APPLIED FOR THE BOTH END OF ODD NUMBER SOLDER TAIL
 4. 材 料: ターミナル:リン青銅、ニッケル下地 銅ビスマスマメッキ (t=0.32)
 MATERIAL: TERMINAL:PHOSPHOR BRONZE, TIN-BISMUTH OVER NICKEL PLATING (t=0.32)
 ハウジング: 66ナイロン, UL94V-0
 HOUSING: 66NYLON,UL94V-0
 アクチュエーター: ポリエステル, UL94V-0
 ACTUATOR: POLYESTER,UL94V-0
 5. 本製品は 52043-**-10 の鉛フリー品である。
 THIS PRODUCT IS LEAD FREE OF 52043-**-10.

11.05	5.2	52043-0419	4
B	A	MATERIAL NO.	極数 CKT.
MODEL NO.		52043-**-19	

REVISED EC NO: J2017-0269 DRWNGES CHKD: APPR:MSASAO	DESCRIPTION 2016/11/17 2016/12/26	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		0.25 UNDER	UNDER	±	DRAWN BY YWADA	DATE 2004/05/19	TITLE 1.0 FPC CONN. Z.I.F R/A			
		0.25 OVER	0.5 UNDER	±	CHECKED BY MSASAO	DATE 2004/05/19	-LEAD FREE- molex			
		0.5 OVER	1.0 UNDER	±	APPROVED BY	DATE				
0 OVER	10 UNDER	±0.2	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-52043-002		SHEET NO. 1 OF 1			
10 OVER	30 UNDER	±0.25	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							